RoHS

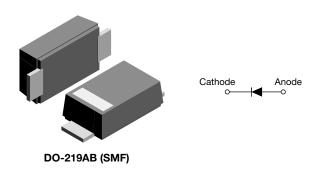
COMPLIANT HALOGEN

FREE



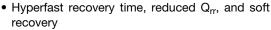
### Vishay Semiconductors

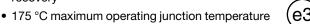
# Hyperfast Rectifier, 1 A FRED Pt®



PRODUCT SUMMARY				
I <sub>F(AV)</sub>	1 A			
$V_{R}$	100 V			
V <sub>F</sub> at I <sub>F</sub> (typ. 125 °C)	0.74 V			
t <sub>rr</sub>	25 ns			
T <sub>J</sub> max.	175 °C			
Package	DO-219AB (SMF)			
Diode variation	Single die			

#### **FEATURES**





- Specified for output and snubber operation
- Low forward voltage drop
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>

#### **DESCRIPTION / APPLICATIONS**

State of the art hyperfast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyperfast recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness, and reliability characteristics.

These devices are intended for use in snubber, boost, lighting, as high frequency rectifiers, and freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Peak repetitive reverse voltage	$V_{RRM}$		100	V	
Average rectified forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 160 °C <sup>(1)</sup>	1	۸	
Non-repetitive peak surge current	I <sub>FSM</sub>	T <sub>J</sub> = 25 °C	35	А	
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-65 to +175	°C	

#### Note

<sup>(1)</sup> Device on PCB with 8 mm x 16 mm soldering lands

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V <sub>BR</sub> , V <sub>R</sub>	Ι <sub>R</sub> = 100 μΑ	100	-	-		
Forward voltage	onward valtage	I <sub>F</sub> = 1 A	-	0.87	0.93	V	
Forward voitage	V <sub>F</sub>	I <sub>F</sub> = 1 A, T <sub>J</sub> = 125 °C	-	0.74	0.8		
Davis and Indiana assument		$V_R = V_R$ rated	-	-	2		
Reverse leakage current I <sub>R</sub>	T <sub>J</sub> = 125 °C, V <sub>R</sub> = V <sub>R</sub> rated	-	0.5	8	μA		
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 100 V	-	5	-	pF	



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
		$I_F = 1 A, dI_F/dt = 50 A$	/μs, V <sub>R</sub> = 30 V	-	24	-	
Reverse recovery time		$I_F = 0.5 \text{ A}, I_R = 1 \text{ A}, I_{rr}$	0.5 A, I <sub>R</sub> = 1 A, I <sub>rr</sub> = 0.25 A		-	25	
neverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	16	-	ns
		T <sub>J</sub> = 125 °C		-	23	-	
Peak recovery current	1	T <sub>J</sub> = 25 °C	$I_F = 1 \text{ A}$	-	1.6	-	Α
Peak recovery current I <sub>RRM</sub>	T <sub>J</sub> = 125 °C	dl <sub>F</sub> /dt = 200 A/µs V <sub>R</sub> = 160 V		2.5	-	_ A	
Develope vecessers above	0	T <sub>J</sub> = 25 °C		-	13	ı	nC
Reverse recovery charge	everse recovery charge Q <sub>rr</sub>	T <sub>J</sub> = 125 °C		-	30	ı	110

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-65	-	+175	°C
Thermal resistance, junction to case	R <sub>thJC</sub>	Device mounted on PCB with 8 mm x 16 mm soldering lands	-	-	17	°C/W
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Device mounted on PCB with 2 mm x 3.5 mm soldering lands	-	-	140	°C/W
Approximate weight				0.015		g
Approximate weight				0.0005		OZ.
Marking device		Case style SMF (DO-219AB)		M	AH	

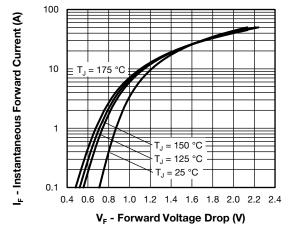


Fig. 1 - Typical Forward Voltage Drop Characteristics

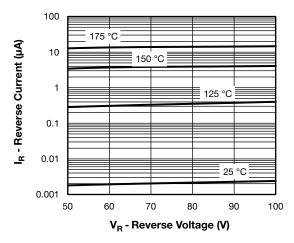


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

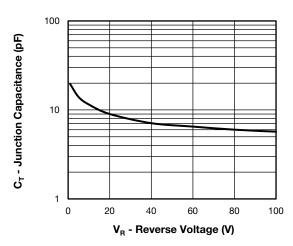


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

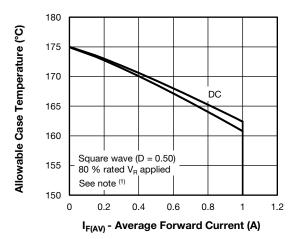


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current

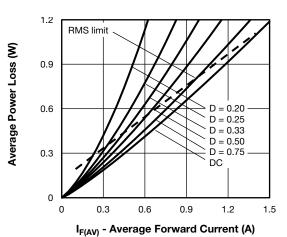
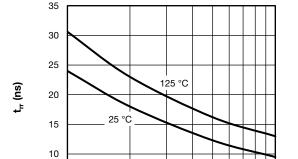


Fig. 5 - Forward Power Loss Characteristics



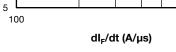


Fig. 6 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

1000

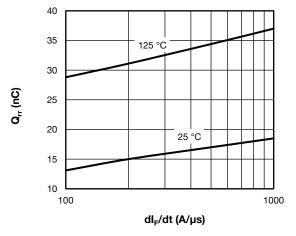
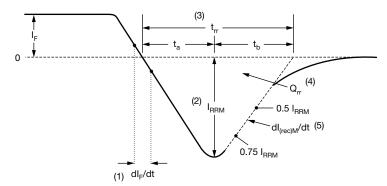


Fig. 7 - Typical Stored Charge vs. dl<sub>F</sub>/dt

### Note

 $\begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 5)}; \\ Pd_{REV} = \text{inverse power loss} = V_{R1} \times I_R \text{ (1 - D)}; I_R \text{ at } V_{R1} = \text{rated } V_R \\ \end{array}$ 



- (1) dl<sub>F</sub>/dt rate of change of current through zero crossing
- (2)  $I_{RRM}$  peak reverse recovery current
- (3)  $\rm t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $\rm I_F$  to point where a line passing through 0.75  $\rm I_{RRM}$  and 0.50  $\rm I_{RRM}$  extrapolated to zero current.
- (4)  $\mathbf{Q}_{rr}$  area under curve defined by  $\mathbf{t}_{rr}$  and  $\mathbf{I}_{RRM}$

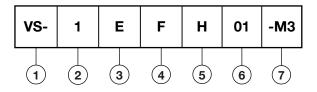
$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) dl<sub>(rec)M</sub>/dt - peak rate of change of current during t<sub>b</sub> portion of t<sub>rr</sub>

Fig. 8 - Reverse Recovery Waveform and Definitions

### **ORDERING INFORMATION TABLE**

### **Device code**



- 1 Vishay Semiconductors product
- 2 Current rating (1 = 1 A)
- 3 Circuit configuration:

E = single diode

- F = SMF package
- **5** Process type,

H = hyperfast recovery

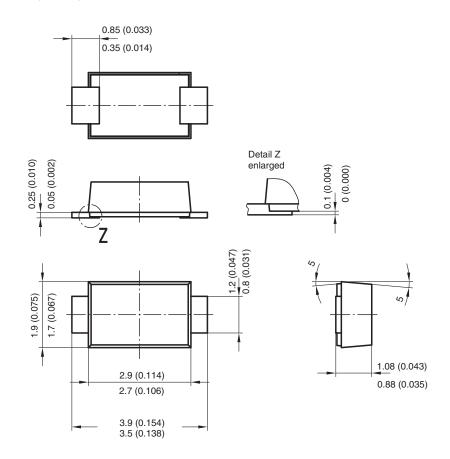
- Voltage code (01 = 100 V)
- 7 -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)					
PREFERRED P/N	QUANTITY PER REEL	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION		
VS-1EFH01-M3/I	10 000	10 000	13"diameter plastic tape and reel		

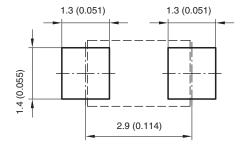
LINKS TO RELATED DOCUMENTS				
Dimensions <u>www.vishay.com/doc?95572</u>				
Part marking information	www.vishay.com/doc?95618			
Packaging information	www.vishay.com/doc?95577			
SPICE model	www.vishay.com/doc?96012			

# **DO-219AB (SMF)**

### **DIMENSIONS** in millimeters (inches)



#### Foot print recommendation:



Created - Date: 15. February 2005 Rev. 3 - Date: 13. March 2007 Document no.:S8-V-3915.01-001 (4)

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